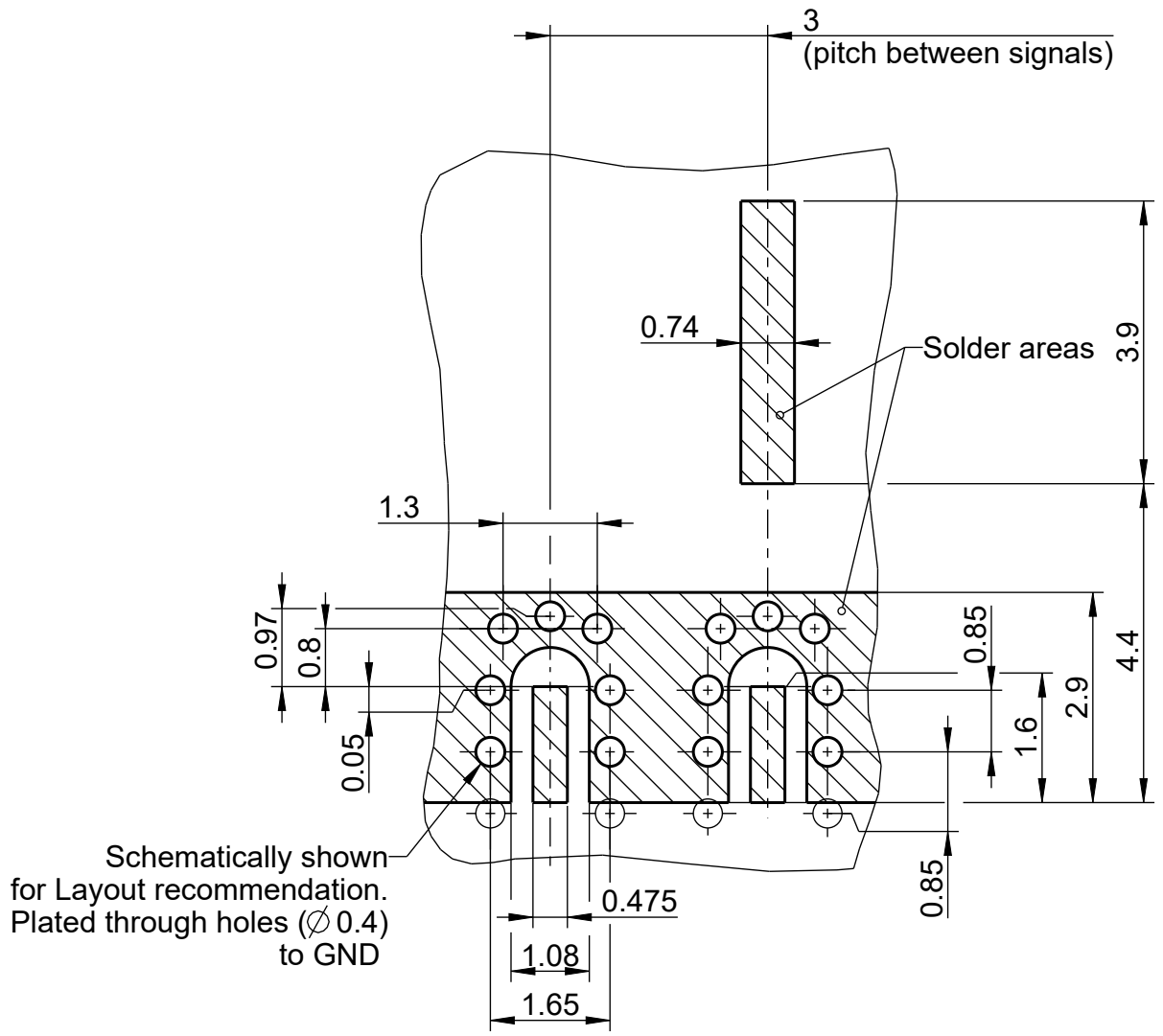
Leiterplatten-Layout
PCB layout
B 501B



A wide variety of transmission line topologies and pcb-parameters like permittivity, substrate thickness, and board-stack up are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.
Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.
In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Rosenberger	general tolerance: ISO 2768 mH	RN 006-01 dimensions <0,5 and symmetry	scale: 5:1 ( )
			weight[g]: 2.873 surface[mm²]: 765.7
			material:
vertraulich / *confidential*		date / name	title: Leiterplatten-Layout *PCB layout*
	drawn	30.05.2016 K_Mitterer	
	check.	17.01.2019 G_Schiele	
	appr.	17.01.2019 M_Moder	
a00 19-s015 A_Ploetz 15.01.2019	dimensioning incl. plating		
300 16-v711 G_Schiele 09.02.2017	Size ISO 14405 (E) Tolerancing ISO 8015		drawing-no.: MB_501B
200 16-m528 K_Mitterer 22.06.2016			sheet: 1 of: 1
100 16-e159 K_Mitterer 06.06.2016			
rev. change-no name date			remarks: MB_501, MB_501A

PD_FB_01
-METRIC-
ISO-Projektion Methode 1